

**Product / Package Information**

Package	LFCSP - Sawn
Body Size (mm)	4 X 5 X 0.75 (2.6 x 3.6 EP)
Lead Count	28
Terminal Finish	100 Sn
MS Number	MS012306D

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.32E-02	84.50	845000	37.66	376553
Thermosets	Epoxy & Phenol Resin	Proprietary	4.11E-03	15.00	150000	6.68	66844
Other inorganic materials	Carbon black	1333-86-4	1.37E-04	0.50	5000	0.22	2228
Subtotal			2.74 E-02	100.00	1000000	44.56	445625

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.91 E-02	97.50	975000	47.27	472727
Copper & its alloys	Iron	7439-89-6	7.01 E-04	2.35	23500	1.14	11394
Copper & its alloys	Zinc	7440-66-6	3.58 E-05	0.12	1200	0.06	582
Copper & its alloys	Phosphorus	7723-14-0	8.95 E-06	0.03	300	0.01	145
Subtotal			2.98 E-02	100.00	1000000	48.48	484848

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.45 E-05	100.0	1000000	0.12	1212

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.41 E-03	100.0	1000000	2.29	22880

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.12 E-04	99.0	990000	0.35	3452
Precious metals	Palladium	7440-05-3	2.14 E-06	1.0	10000	0.003	35
Subtotal			2.14 E-04	100.0	1000000	0.35	3487

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.21 E-03	100.0	1000000	3.60	35955

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.84 E-04	77.00	770000	0.46	4614
Other organic materials	Acrylic resin	Proprietary	2.58 E-05	7.00	70000	0.04	419
Other organic materials	Acrylate	Proprietary	2.03 E-05	5.50	55000	0.03	330
Other organic materials	Polybutadiene derivative	Proprietary	1.66 E-05	4.50	45000	0.03	270
Other organic materials	Epoxy resin	Proprietary	9.21 E-06	2.50	25000	0.01	150
Other organic materials	Butadiene Copolymer	Proprietary	5.53 E-06	1.50	15000	0.01	90
Others	Additive	Proprietary	5.53 E-06	1.50	15000	0.01	90
Others	Peroxide	Proprietary	1.84 E-06	0.50	5000	0.003	30
Subtotal			3.69 E-04	100.0	1000000	0.60	5993

<b>Package Totals</b>			<b>Weight (g)</b> 6.15 E-02			<b>Percentage (%)</b> 100	<b>PPM</b> 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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